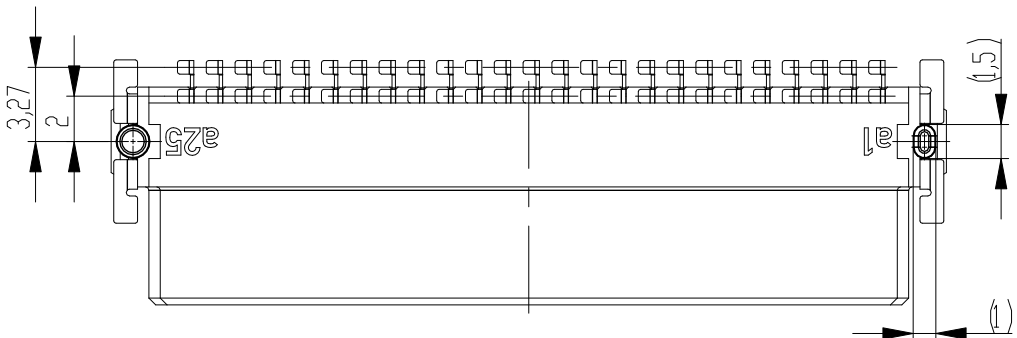
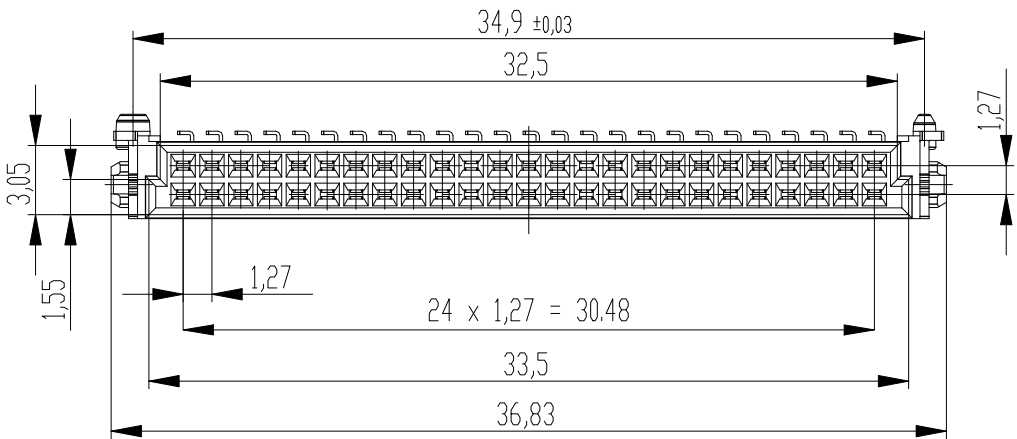
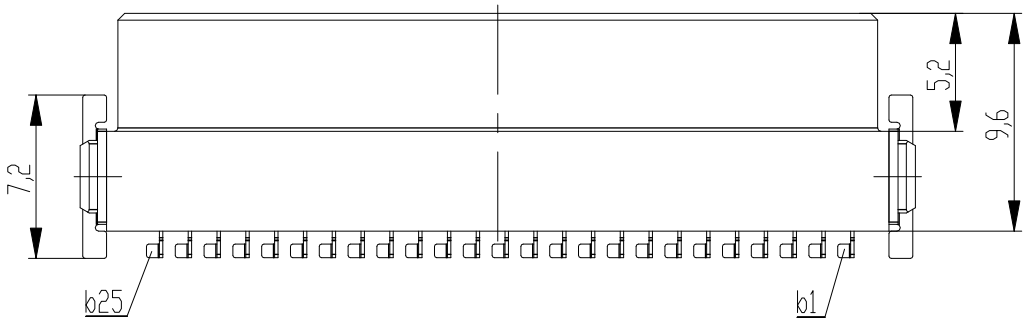
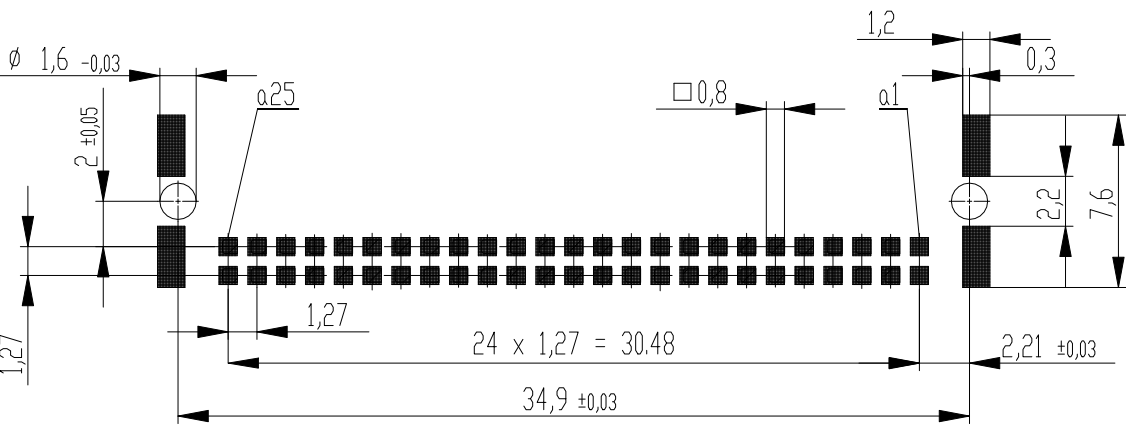
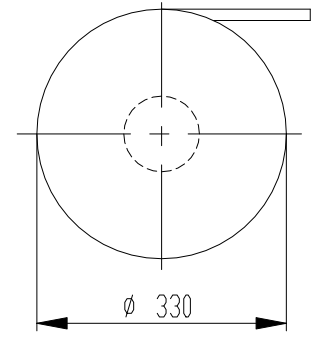


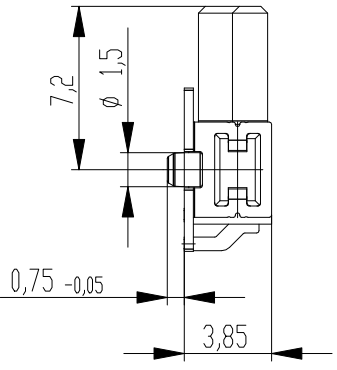
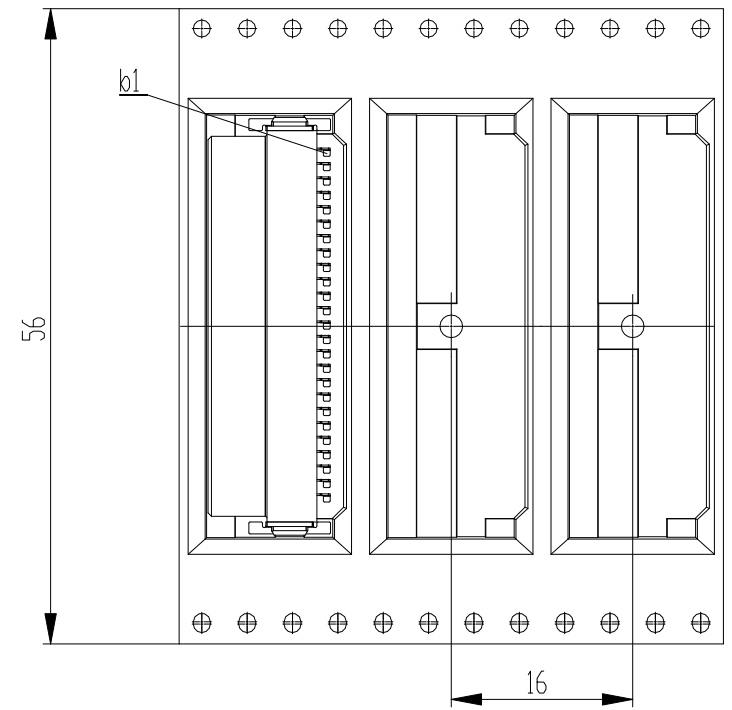
Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs



Abspulrichtung - reel off direction



Anforderungsstufe 1
performance level 1

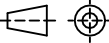
Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinkt 4-6 μm
terminal area 4-6 μm tin plating

Koplanarität der Anschlüsse $\leq 0,1 \text{ mm}$
coplanarity area of termination $\leq 0,1 \text{ mm}$

BA7-03 - Standard Bauhöhe
type7-03 - Standard Assembly Height

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The German version of this drawing has been offered for convenience only and may deviate from the English original.
In case of any deviation the English version shall prevail.

Dimension no.				Tolerances Dim. for Information ISO 8015		 All Dimensions in mm	Scale 5:1		
							Material		
<u>Customer drawing:</u> THIS DRAWING IS A CONTROLLED DOCUMENT.				Subject to modification without prior notice. Drawing will not be updated.			ERNI-Federl. SMC-Q 50-SMD-BA7-03 Female SMC-Q 50-SMD-type7-03		
				 TE Connectivity			©=154742-E		I
									A3
h		04.02.2020					Class SMCQ		
Index		Date							